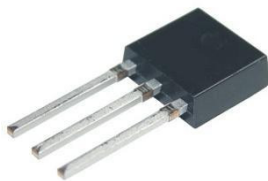


Low collector saturation voltage, collector power dissipation, complementary to 2SD880I.



h_{FE} Classifications & Marking

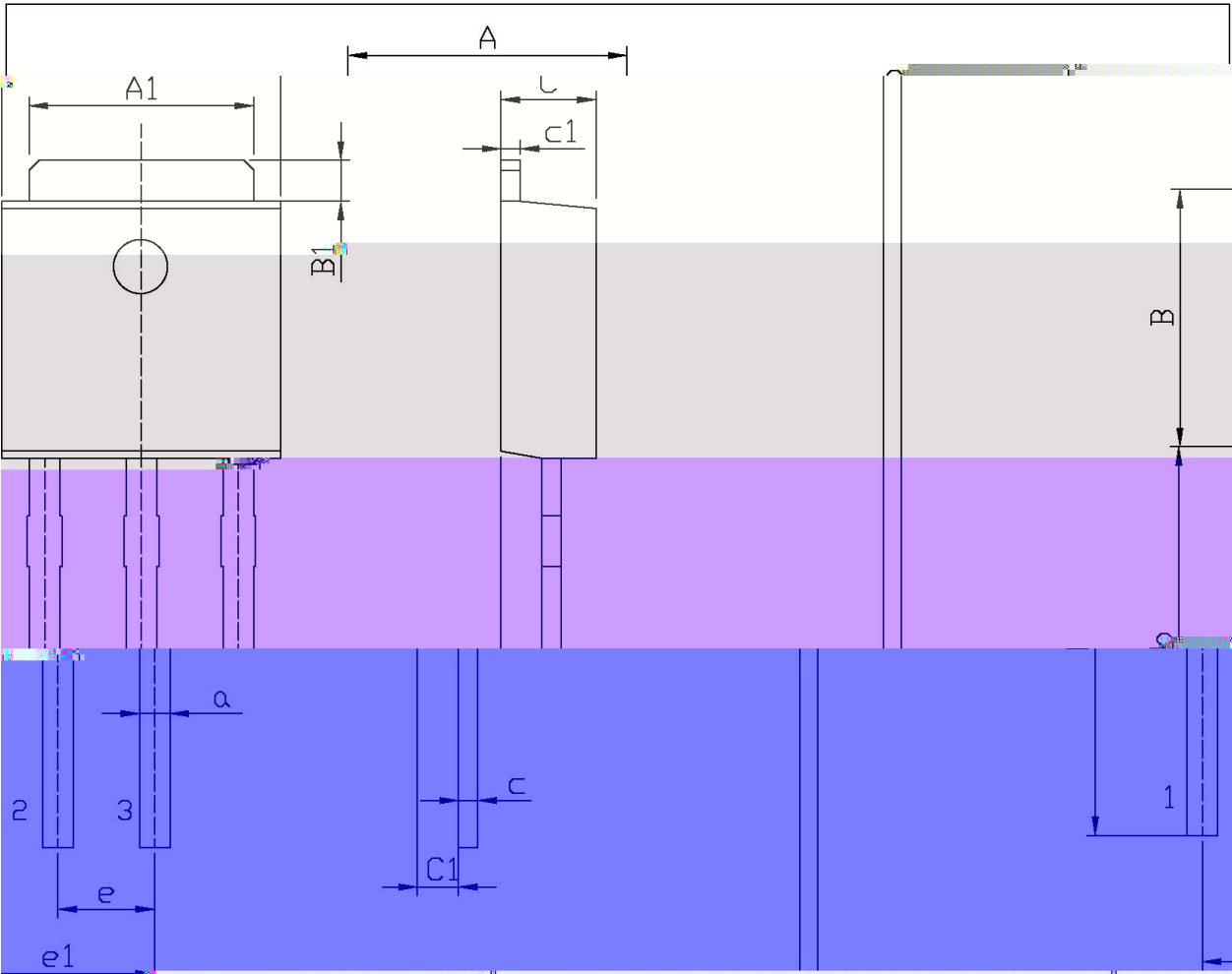
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-60	V
Emitter to Base Voltage	V_{EBO}	-7.0	V
Collector Current - Continuous	I_C	-3.0	A
Base Current - Continuous	I_B	-0.5	A
Collector Power Dissipation	P_C	1.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-50mA$ $I_B=0$	-60			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-60V$ $I_E=0$			-100	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-7.0V$ $I_C=0$			-100	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE}=-5.0V$ $I_C=-0.5A$	60		300	
	$h_{FE(2)}$	$V_{CE}=-5.0V$ $I_C=-3.0A$	20			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-3.0A$ $I_B=-0.3A$		-0.5	-1.0	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=-5.0V$ $I_C=-0.5A$		-0.7	-1.0	V
Transition Frequency	f_T	$V_{CE}=-5.0V$ $I_C=-0.5A$		9.0		MHz
Collector output capacitance	C_{ob}	$V_{CB}=-10V$ $I_E=0$ $f=1.0MHz$		150		pF
Turn-On Time	t_{on}	$-I_{B1}=I_{B2}=0.2A$		0.4		μS
Storage Time	t_{stg}			1.7		
Fall Time	t_f			0.5		

/ Package Dimensions



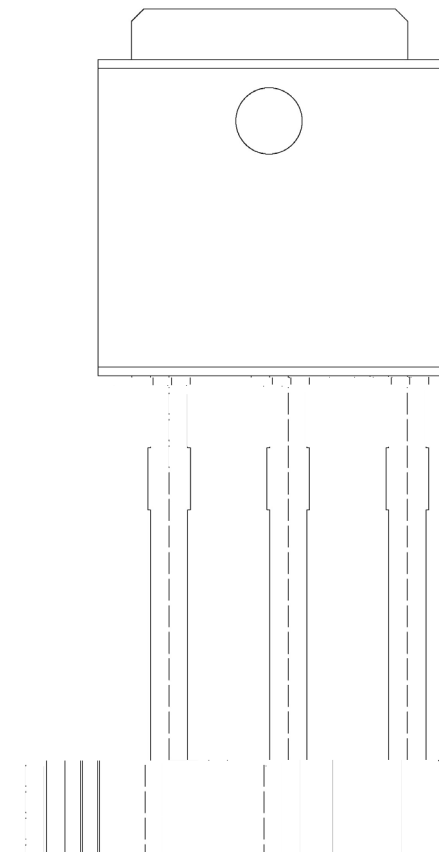
单位: mm

DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
Symbol	Min	Max	Symbol	Min	Max
b	9.00	9.40	A1	5.10	5.50
c	0.45	0.55	B1	0.95	1.25
c1	0.45	0.55	C	2.20	2.40
e	2.24	2.34	C1	0.95	1.15
e1	4.43	4.73			

251

TO-

/ Marking Instructions



BR

B834I

Y: h_{FE}

Note:

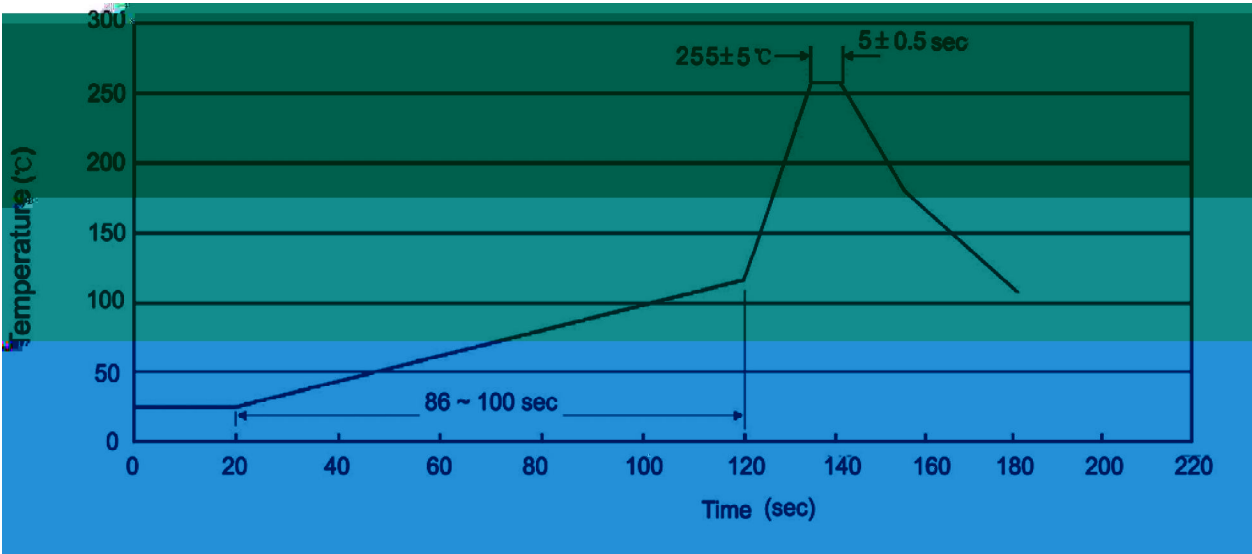
BR: Company Code

B834I: Product Type.

Y: h_{FE} Classifications Symbol

****:

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec
-------	-----------	-------------	---------------

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量
----------------------	------------